Thin Film High Power AlN Chip

Electronics

TFHP Series

Features:

- Power rating 6W in 2512 size
- Power rating 2W in 1206 size
- Aluminium nitride substrate
- Large termination soldering area
- Precision to 0.1%, 25ppm/°C





All parts are Pb-free and comply with EU Directive 2011/65/EU amended by (EU) 2015/863

Electrical Data

		1206	2512	
Power rating ¹ at 70°C W		2	6	
Limiting element voltage	V	100		
Resistance range	Ω	50R to 30K1		
Resistance tolerance	%	0.1, 0.25, 0.5, 1		
TCR	ppm/°C	25, 50		
Standard values		E24 & E96		
Ambient temperature range	°C	-55 to +155		

Note: 1. Dependent on mounting conditions.

Physical Data

Dimensions in mm and weight in mg						C	
	L	W	T	Α	С	Wt. nom.	
1206	3.05 ±0.2	1.55 ± 0.2	0.43 ± 0.15	1.2 ± 0.2	0.5 ± 0.15	11.0	A
2512	6.3 ± 0.2	3.1 ± 0.2	0.45 ± 0.15	1.6 ± 0.25	0.7 ± 0.25	42.3	L A W
Recommended mounting pad dimensions in mm							c
	,	Α	E	3	С		<i>□□□</i>
1206	0.6 1.9		1.8		_B _A		
2512	2 2.77		2.31		3.2		

Construction

A thin-film material is selectively deposited on an aluminium nitride substrate together with metallic contacts at each end of the resistor. The unadjusted resistors are heat treated to give the required TCR and stability, then a precisely controlled laser trim process adjusts the resistance value. Epoxy protection is applied, and wrap-around terminations are added and tin (Sn) plated. Each resistor is measured immediately before packing into tape.

Marking

TFHP resistors are marked white on black with 3 or 4 characters indicating ohmic value.

www.ttelectronics.com/resistors

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Thin Film High Power AIN Chip



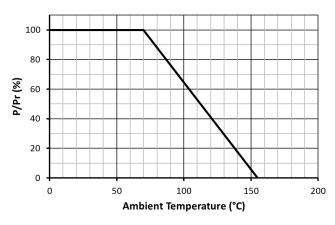


Performance Data

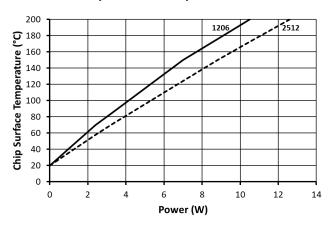
Test	Method	-	Maximum
Load Life	1000 hours, cyclic load P _r at T _A = 70°C	±ΔR%	1
Short Term Overload	Lesser of 6.25 x P _r or 2 x LEV for 2 s	±ΔR%	0.5
Damp Heat with Load	1000 hours, cyclic load P _r at 40°C, 90-95%RH	±ΔR%	0.4
Low Temperature Operation	1 hour at -55°C, 45 minutes P _r	±ΔR%	0.2
High Temperature Exposure	1000 hours at +155°C	±ΔR%	0.2
Thermal Shock	100 cycles, -55 to +155°C	±ΔR%	0.2
Resistance to Solder Heat	260 ± 5°C, 10 ± 1s	±ΔR%	0.2
Solderability	245 ± 5°C, 3s		≥95% coverage
Insulation Resistance	100V _{dc} , 60s	·	≥10G

Thermal Performance Data

Temperature Derating



Chip Surface Temperature



Mounting

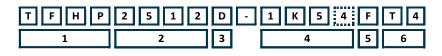
The above chip surface temperature readings were made by thermal camera under room temperature conditions with the component mounted at the centre of a 40×90 mm test board with double sided $70 \mu m$ (20z) copper connected with thermal vias.

Packaging

TFHP resistors are packed in tape which is paper for 1206 and plastic for 2512, on 178mm reels. For full details of tape and reel dimensions see https://www.ttelectronics.com/ttelectronics/media/productfiles/applicationnotes/ps001-packing-of-general-purpose-chip-resistors.pdf

Ordering Procedure

Example: TFHP2512D-1K54FT4 (2512, 25ppm/°C, 1.54 kilohms ±1%, Pb-free)



1	2	3	4	5	6		5
Type	Size	TCR	Value	Tolerance	Packing		king
TFHP	1206	$D = \pm 25ppm/^{\circ}C$	E24 or E96	B = ±0.1%	T5	1206	5000/reel
	2512	$C = \pm 50 ppm/^{\circ}C$	3/4 characters	$C = \pm 0.25\%$	T4	2512	4000/reel
			R = ohms	$D = \pm 0.5\%$			
			K = kilohms	F = ±1%			